

# 1 Characteristics

**Table 1. Absolute ratings (limiting values, at 25 °C, unless otherwise specified)**

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		600	V
$I_{F(RMS)}$	Forward rms current		50	A
$I_{F(AV)}$	Average forward current	$T_C = 103\text{ °C}$ , $\delta = 0.5$ square	30	A
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10\text{ ms}$ sinusoidal	D <sup>2</sup> PAK, D <sup>2</sup> PAK HV	A
			TO-220AC, DO-247, DO-247 LL	
$T_{stg}$	Storage temperature range		-65 to +175	°C
$T_j$	Maximum operating junction temperature		175	°C

**Table 2. Thermal parameters**

Symbol	Parameter	Max. value	Unit
$R_{th(j-c)}$	Junction to case	0.70	°C/W
$R_{th(j-c)}$	Junction to case DO-247 LL	0.90	°C/W

For more information, please refer to the following application note:

- AN5088: Rectifiers thermal management, handling and mounting recommendation

**Table 3. Static electrical characteristics**

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-		40	$\mu\text{A}$
		$T_j = 150\text{ °C}$		-	80	800	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 15\text{ A}$	-		2.45	V
		$T_j = 150\text{ °C}$		-	1.15	1.45	
		$T_j = 25\text{ °C}$	$I_F = 30\text{ A}$	-		2.95	
		$T_j = 150\text{ °C}$		-	1.45	1.85	

1. Pulse test:  $t_p = 5\text{ ms}$ ,  $\delta < 2\%$

2. Pulse test:  $t_p = 380\text{ }\mu\text{s}$ ,  $\delta < 2\%$

To evaluate the conduction losses, use the following equation:

$$P = 1.05 \times I_{F(AV)} + 0.026 \times I_F^2 (RMS)$$

For more information, please refer to the following application notes related to the power losses:

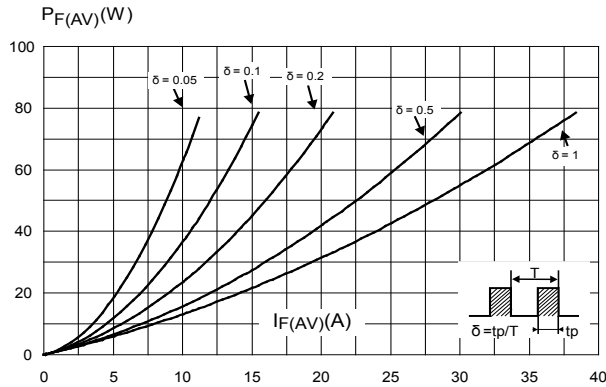
- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode
- AN5028: Calculation of turn-off power losses generated by an ultrafast diode

**Table 4. Dynamic electrical characteristics**

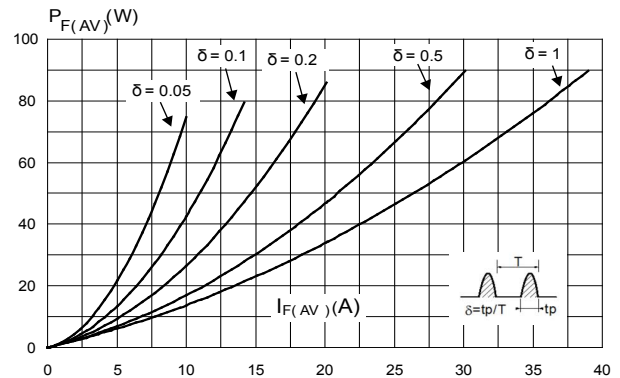
Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$t_{rr}$	Reverse recovery time	$T_J = 25\text{ }^{\circ}\text{C}$	$I_F = 0.5\text{ A}, I_R = 1\text{ A}, I_{rr} = 0.25\text{ A}$	-		30	ns
			$I_F = 1\text{ A}, V_R = 30\text{ V}, dI_F/dt = -50\text{ A}/\mu\text{s}$	-	40	55	
$I_{RM}$	Reverse recovery current	$T_J = 125\text{ }^{\circ}\text{C}$	$I_F = 30\text{ A}, V_R = 400\text{ V}, dI_F/dt = -200\text{ A}/\mu\text{s}$	-	8	11	A
$Q_{RR}$	Reverse recovery charge			-	485		nC
$t_{rr}$	Reverse recovery time			-	95		ns

## 1.1 Characteristics (curves)

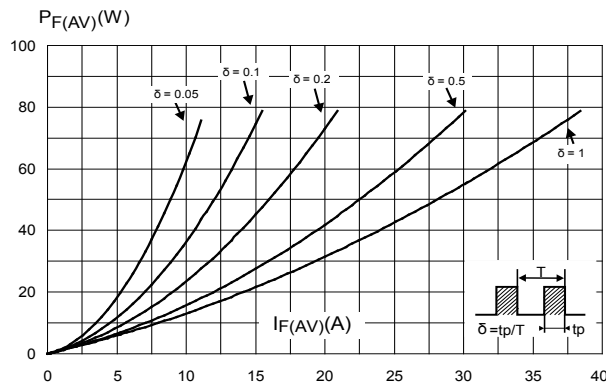
**Figure 1. Average forward power dissipation versus average forward current (square waveform)**



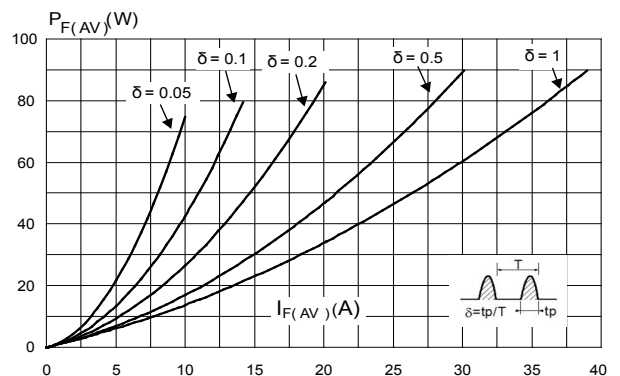
**Figure 2. Average forward power dissipation versus average forward current (sinusoidal waveform)**



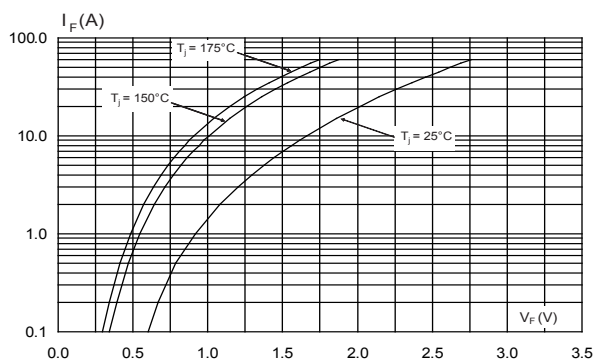
**Figure 3. Average forward power dissipation versus average forward current (square waveform, DO-247 LL)**



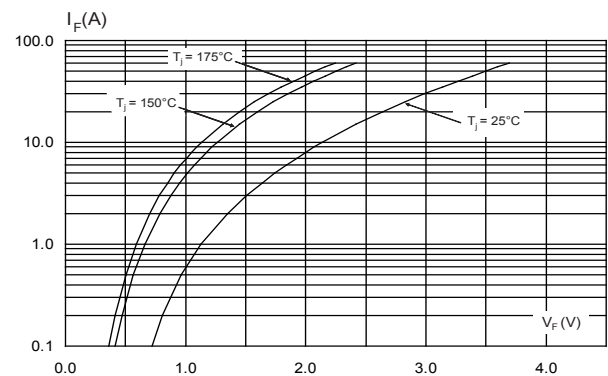
**Figure 4. Average forward power dissipation versus average forward current (sinusoidal waveform, DO-247 LL)**

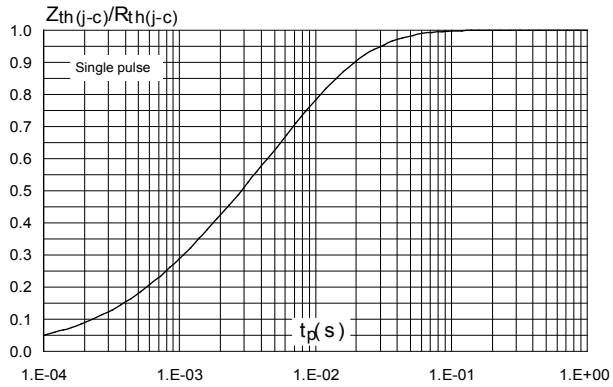
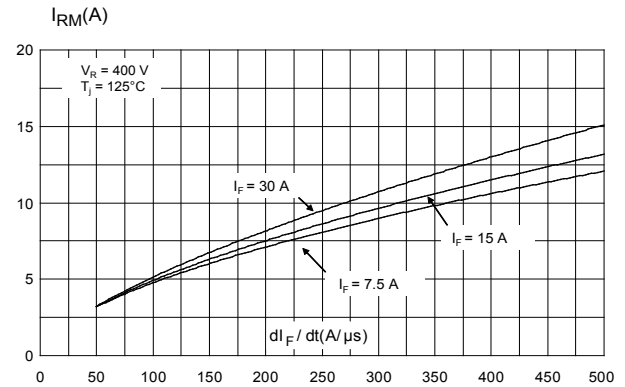
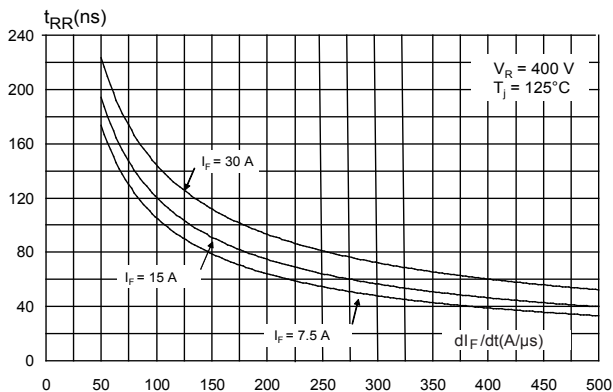
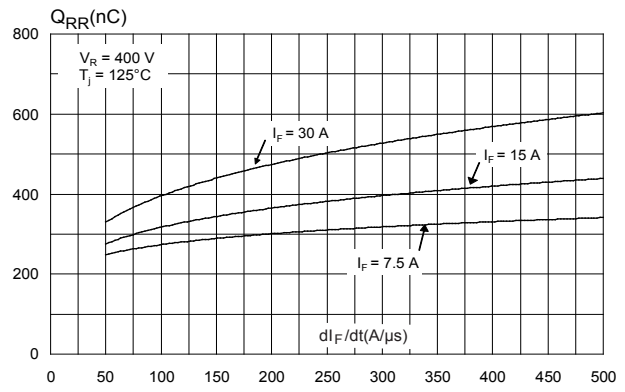
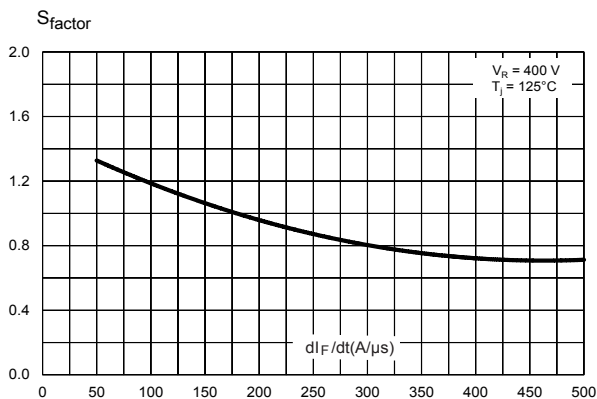
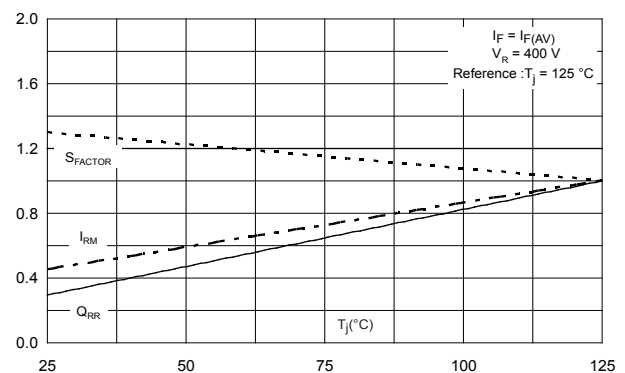


**Figure 5. Forward voltage drop versus forward current (typical values)**

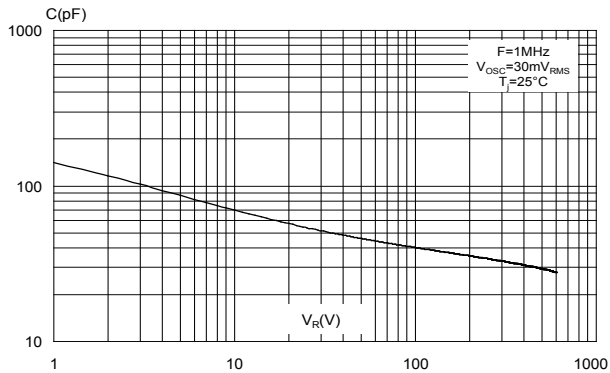


**Figure 6. Forward voltage drop versus forward current (maximum values)**

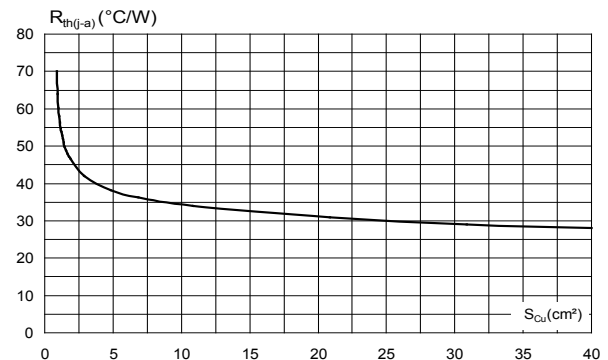


**Figure 7. Relative variation of thermal impedance junction to case versus pulse duration**

**Figure 8. Peak reverse recovery current versus  $dl_F/dt$  (typical values)**

**Figure 9. Reverse recovery time versus  $dl_F/dt$  (typical values)**

**Figure 10. Reverse recovery charges versus  $dl_F/dt$  (typical values)**

**Figure 11. Reverse recovery softness factor versus  $dl_F/dt$  (typical values)**

**Figure 12. Relative variations of dynamic parameters versus junction temperature**


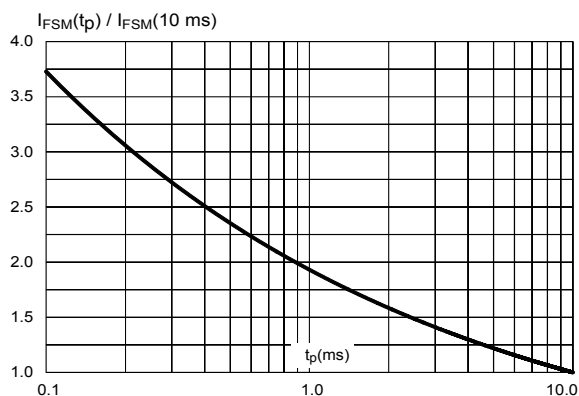
**Figure 13. Junction capacitance versus reverse voltage applied (typical values)**



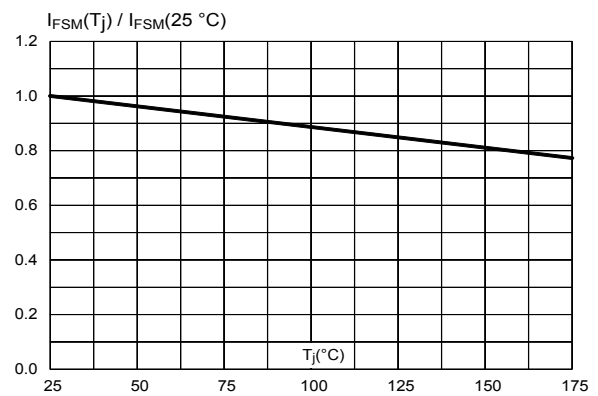
**Figure 14. Thermal resistance junction to ambient versus copper surface under tab (typical values, epoxy printed board FR4,  $e_{Cu} = 35 \mu\text{m}$ )(D<sup>2</sup>PAK and D<sup>2</sup>PAK HV)**



**Figure 15. Relative variation of non-repetitive peak surge forward current versus pulse duration (sinusoidal waveform)**



**Figure 16. Relative variation of non-repetitive peak surge forward current versus initial junction temperature (sinusoidal waveform)**



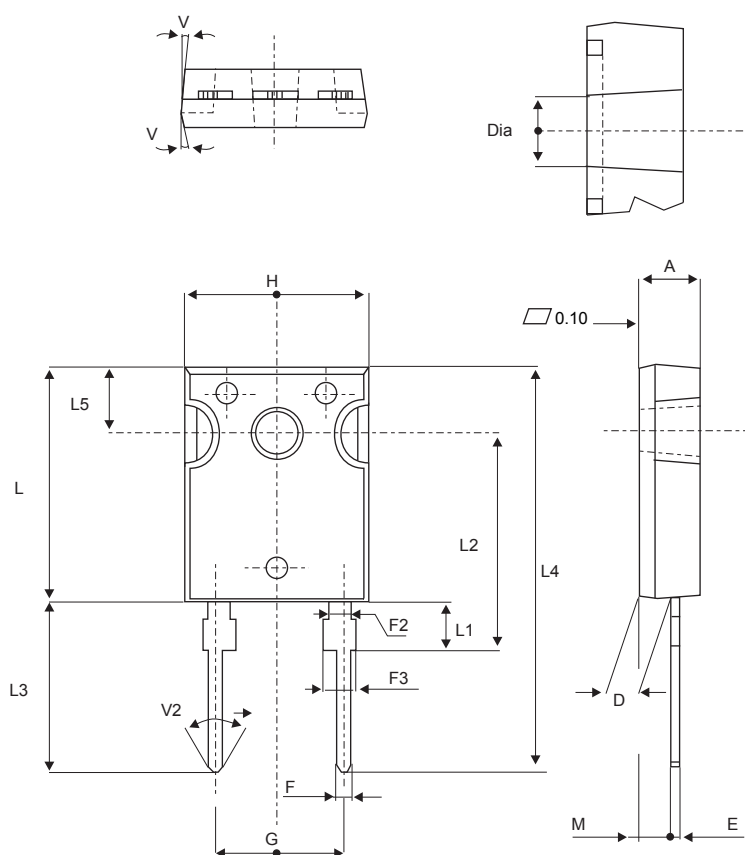
## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 2.1 DO-247 package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.8 N·m (DO-247)
- Maximum torque value: 1.0 N·m (DO-247)

**Figure 17. DO-247 package outline**



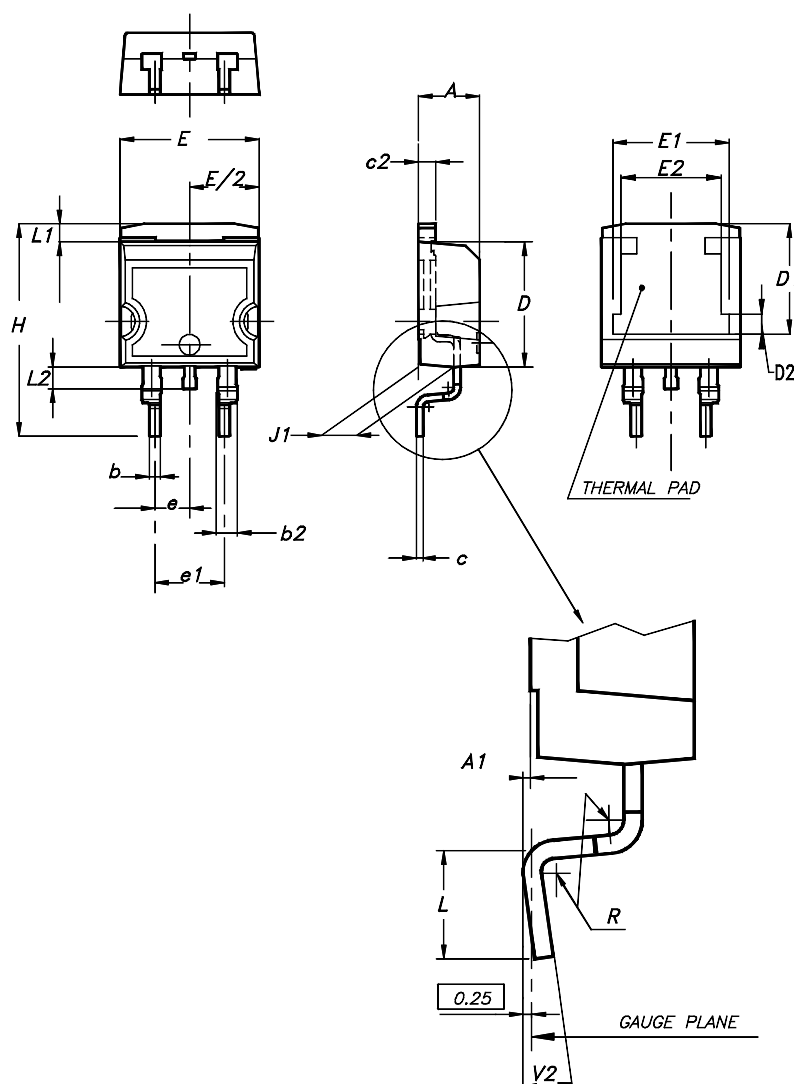
**Table 5. DO-247 package mechanical data**

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.85	5.15	0.191	0.203
D	2.20	2.60	0.086	0.102
E	0.40	0.80	0.015	0.031
F	1.00	1.40	0.039	0.055
F2	2.00 typ.		0.078 typ.	
F3	2.00	2.40	0.078	0.094
G	10.90 typ.		0.429 typ.	
H	15.45	15.75	0.608	0.620
L	19.85	20.15	0.781	0.793
L1	3.70	4.30	0.145	0.169
L2	18.50 typ.		0.728 typ.	
L3	14.20	14.80	0.559	0.582
L4	34.60 typ.		1.362 typ.	
L5	5.50 typ.		0.216 typ.	
M	2.00	3.00	0.078	0.118
V	5°		5°	
V2	60°		60°	
Dia.	3.55	3.65	0.139	0.143

## 2.2 D<sup>2</sup>PAK package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)

**Figure 18. D<sup>2</sup>PAK package outline**

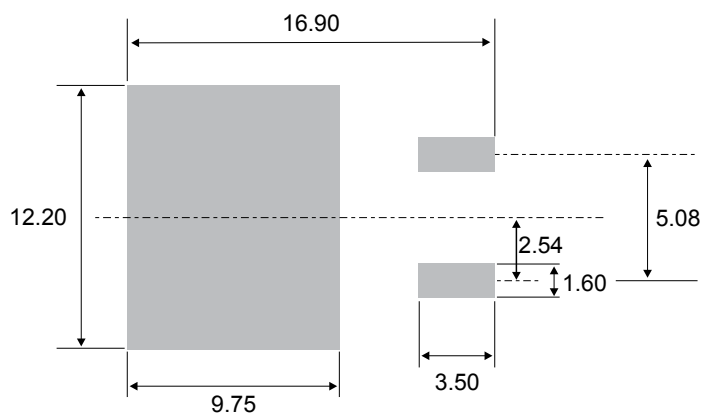


**Note:** This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.



**Table 6. D<sup>2</sup>PAK package mechanical data**

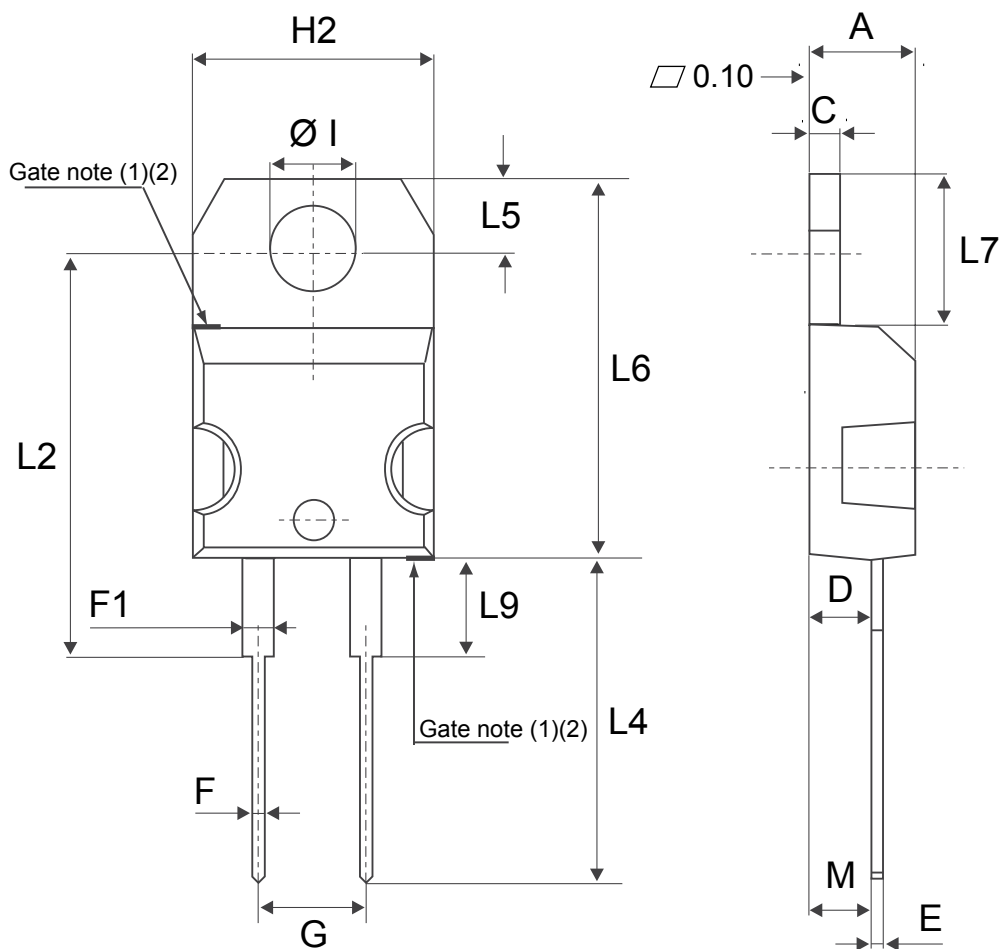
Ref.	Dimensions			
	Millimeters		Inches (for reference only)	
	Min.	Max.	Min.	Max.
A	4.36	4.60	0.172	0.181
A1	0.00	0.25	0.000	0.010
b	0.70	0.93	0.028	0.037
b2	1.14	1.70	0.045	0.067
c	0.38	0.69	0.015	0.027
c2	1.19	1.36	0.047	0.053
D	8.60	9.35	0.339	0.368
D1	6.90	8.00	0.272	0.311
D2	1.10	1.50	0.043	0.060
E	10.00	10.55	0.394	0.415
E1	8.10	8.90	0.319	0.346
E2	6.85	7.25	0.266	0.282
e	2.54 typ.		0.100	
e1	4.88	5.28	0.190	0.205
H	15.00	15.85	0.591	0.624
J1	2.49	2.90	0.097	0.112
L	1.90	2.79	0.075	0.110
L1	1.27	1.65	0.049	0.065
L2	1.30	1.78	0.050	0.070
R	0.4 typ.		0.015	
V2	0°	8°	0°	8°

**Figure 19. D<sup>2</sup>PAK recommended footprint (dimensions in mm)**


## 2.3 TO-220AC package information

- Epoxy meets UL 94,V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.55 N·m
- Maximum torque value: 0.70 N·m

**Figure 20. TO-220AC package outline**



(1) :Max resin gate protusion 0.5 mm

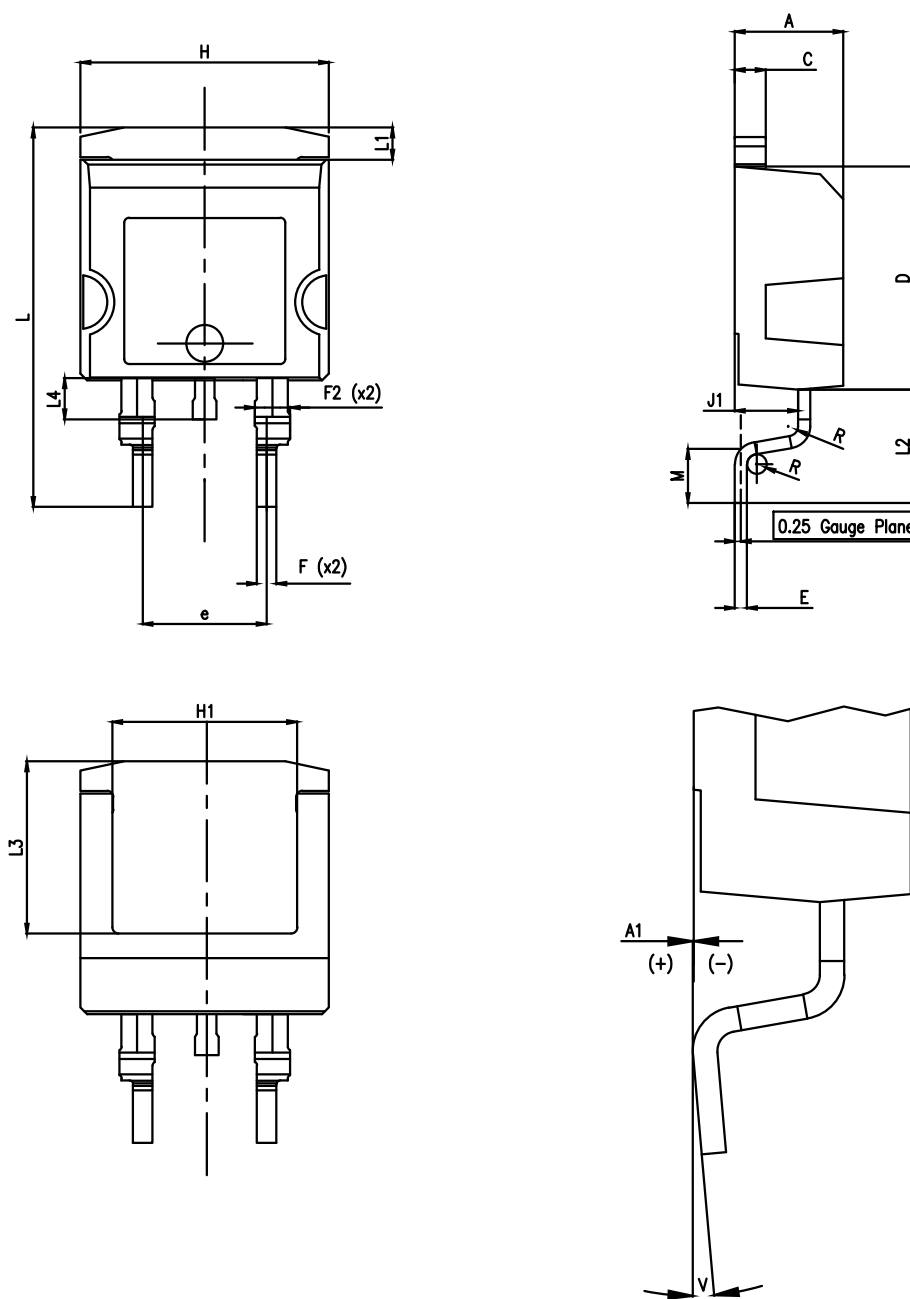
(2) :Resin gate position is accepted in each of the two positions shown on the drawings or their symmetrical

**Table 7. TO-220AC package mechanical data**

Ref.	Dimensions			
	Millimeters		Inches (for reference only)	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
H2	10.00	10.40	0.393	0.409
L2	16.40 typ.		0.645 typ.	
L4	13.00	14.00	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.60 typ.		0.102 typ.	
Diam	3.75	3.85	0.147	0.151

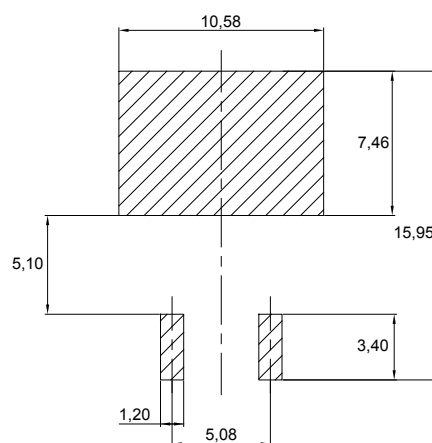
## 2.4 D<sup>2</sup>PAK HV package information

**Figure 21.** D<sup>2</sup>PAK high voltage package outline



**Table 8. D<sup>2</sup>PAK high voltage package mechanical data**

Ref.	Dimensions		
	Min.	Typ.	Max.
A	4.30		4.70
A1	-0.05		0.08
C	1.17		1.37
D	8.95		9.35
e	4.98		5.18
E	0.50		0.90
F	0.78		0.85
F2	1.20		1.60
H	10.00		10.40
H1	7.40		7.80
J1	2.49		2.69
L	15.30		15.80
L1	1.27		1.40
L2	4.93		5.23
L3	6.85		7.25
L4	1.5		1.7
M	2.6		2.9
R	0.20		0.60
V	0°		8°

**Figure 22. D<sup>2</sup>PAK High Voltage footprint in mm**


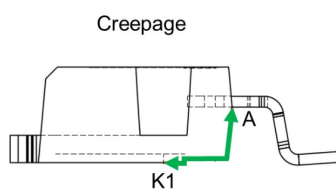
## 2.4.1 Creepage distance between anode and cathode

**Table 9. Creepage distance between anode and cathode**

Symbol	Parameter		Value	Unit
Cd <sub>A-K1</sub>	Minimum creepage distance between A and K1 (with top coating)	D <sup>2</sup> PAK HV	5.38	mm
Cd <sub>A-K2</sub>	Minimum creepage distance between A and K2 (without top coating)		3.48	

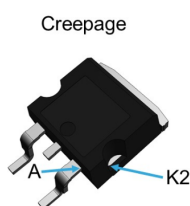
*Note:* D<sup>2</sup>PAK HV creepage distance (anode to cathode) = 5.38 mm min. (refer to IEC 60664-1)

**Figure 23. Creepage with top coating**



Minimum distance between A & K1 = 5.38 mm (with top coating)

**Figure 24. Creepage without top coating**

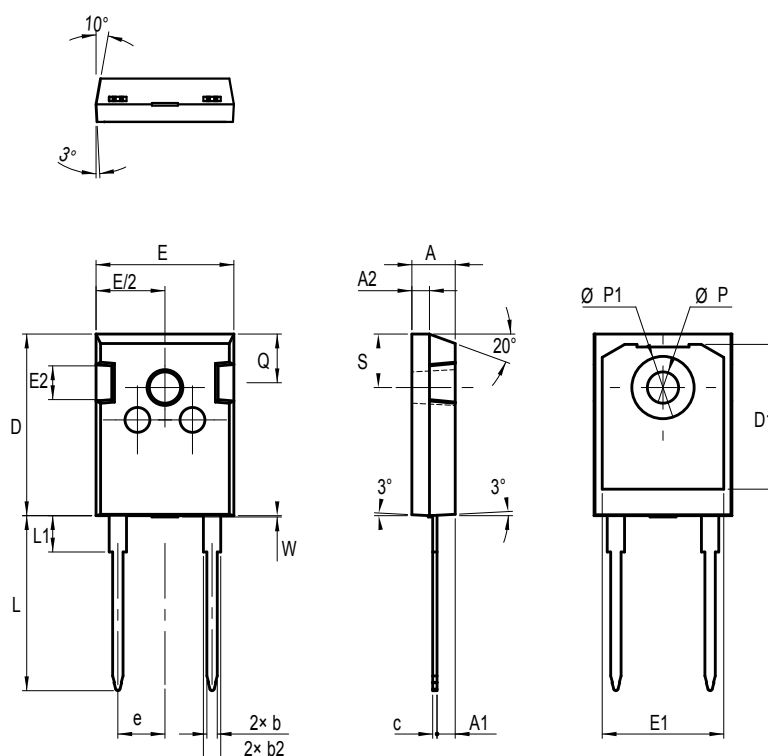


Minimum distance between A & K2 = 3.48 mm (without top coating)

## 2.5 DO-247 LL package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.8 N·m
- Maximum torque value: 1.0 N·m

**Figure 25. DO-247 LL package outline**



**Table 10. DO-247 LL package mechanical data**

Ref.	Dimensions			
	Millimeters		Inches (for reference only)	
	Min.	Max.	Min.	Max.
A	4.70	5.31	0.185	0.209
A1	2.21	2.59	0.087	0.102
A2	1.50	2.49	0.059	0.098
b	0.99	1.40	0.039	0.055
b2	1.65	2.39	0.065	0.094
c	0.38	0.89	0.015	0.035
D	20.80	21.46	0.819	0.845
D1	13.08		0.515	
E	15.49	16.26	0.610	0.640
e	5.44 typ.		0.214	
E1	13.46		0.530	
E2	3.43	3.99	0.135	0.157
L	19.81	20.32	0.780	0.800
L1		4.50		0.177
P	3.56	3.66	0.140	0.144
P1	7.06	7.39	0.278	0.291
Q	5.38	6.20	0.219	0.244
S	6.17 typ.		0.243	
W		0.15		0.006



### 3 Ordering information

**Table 11. Ordering information**

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STTH30RQ06G-TR	STTH30RQ06G	D <sup>2</sup> PAK	1.48 g	1000	Tape and reel
STTH30RQ06D	STTH30RQ06D	TO-220AC	1.86 g	50	Tube
STTH30RQ06W	STTH30RQ06W	DO-247	4.40 g	30	Tube
STTH30RQ06G2-TR	TH30RQ06G2	D <sup>2</sup> PAK HV	1.48 g	1000	Tape and reel
STTH30RQ06WL	STTH30RQ06WL	DO-247 LL	5.9 g	30	Tube

## Revision history

**Table 12. Document revision history**

Date	Revision	Changes
12-Jun-2017	1	Initial release.
11-Oct-2018	2	Added D <sup>2</sup> PAK HV package.
20-Nov-2018	3	Updated Features and Table 9. Creepage distance between anode and cathode. Added Figure 24. Creepage without top coating.
02-Mar-2020	4	Added DO-247 LL package information.
30-Mar-2020	5	Updated Figure 1 and Figure 2. Added Figure 3 and Figure 4.

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